Product Change Notification

The information below reflects a change that is being implemented.

Notice Date:	10/08/2007
Product Category:	Battery Management; Linear Devices; Mixed Signal Devices; Power Management; Supervisor; Thermal Management; dsPIC; CAN Communication; Infrared Communication; LIN Communication; Serial Communication; 24xxx; 25xxx; 93xxx; Other; PIC10xxx; PIC12xxx; PIC16xxx; PIC18xxx; PIC24xxx; PSxxx; RFID; SDP
Notification Subject:	CCB#763.01-763.03: QUALIFICATION OF GE800 MOLD COMPOUND IN ASSORTED PDIP/SPDIP PACKAGES AT ALPH

Notification Body:

All Microchip Catalog Part#s Affected For:
8L PDIP assembled at ALPH (CCB# 763.01, for GE800 Mold Compound)
14L/16L/20L PDIP assembled at ALPH (CCB# 763.02, for GE800 Mold Compound)
28L SPDIP assembled at ALPH (CCB# 763.03, for GE800 Mold Compound)

Description of Change:
CHANGE IN BOM

Impacts to Data Sheet:
NONE

Reason for Change:
CONVERSION TO GE800 MOLD COMPOUND

Estimated Change Implementation Date(s):
OCTOBER 31, 2007

Markings to Distinguish Revised From Unrevised Devices:
(e.g.: Date Code, Device Marking, Ship Container Marking)